



Receipt
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: 09/852,824 Filed: May 10, 2001
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: P002-2

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REQUEST FOR CORRECTED FILING RECEIPT

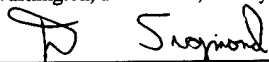
Attached is a copy of the official filing receipt received from the Patent and Trademark Office in the captioned-application for which a corrected filing receipt is respectfully requested.

Under Applicant(s), the inventor's middle name should be "W.C.".

Under Assignment for Published Patent Application, the ".,," should be deleted.

The corrections are noted in red ink on the attached copy of the filing receipt.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on July 14, 2001.

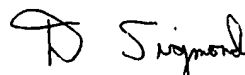


David M. Sigmond
Attorney for Applicant

7/14/01

Date of Signature

Respectfully submitted,



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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/852,824	05/10/2001	2812	750	P002-2	4	55	5

CONFIRMATION NO. 5435

FILING RECEIPT



OC000000006273637

David M. Sigmond
2440 Andrew Drive
Superior, CO 80027

Date Mailed: 07/09/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

W.C.

Charles Wen Chyang Lin, Singapore, SINGAPORE;

Assignment For Published Patent Application

Charles W.C. Lin; delete

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A CON OF 09/465,024 12/16/1999

Foreign Applications

SINGAPORE 9804817-6 12/17/1998

If Required, Foreign Filing License Granted 07/09/2001

Projected Publication Date: 10/18/2001

Non-Publication Request: No

Early Publication Request: No

** SMALL ENTITY **

Title

Bumpless flip chip assembly with solder via

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CONFIRMATION NO. 5435



Bib Data Sheet

SERIAL NUMBER 09/852,824	FILING DATE 05/10/2001 RULE	CLASS 438	GROUP ART UNIT 2812	ATTORNEY DOCKET NO. P002-2	
APPLICANTS Charles W.C. Lin, Singapore, SINGAPORE; ** CONTINUING DATA ***** YES THIS APPLICATION IS A CON OF 09/465,024 12/16/1999 <i>Pat 6,319,751</i> ** FOREIGN APPLICATIONS ***** YES SINGAPORE 9804817-6 12/17/1998 IF REQUIRED, FOREIGN FILING LICENSE GRANTED** SMALL ENTITY ** ** 07/09/2001					
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance <i>DMC</i> Verified and Acknowledged Examiner's Signature _____ Initials _____		STATE OR COUNTRY SINGAPORE	SHEETS DRAWING 4	TOTAL CLAIMS 55	INDEPENDENT CLAIMS 5
ADDRESS David M. Sigmond 2440 Andrew Drive Superior, CO 80027					
TITLE Bumpless flip chip assembly with solder via					
FILING FEE RECEIVED 750	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees		
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